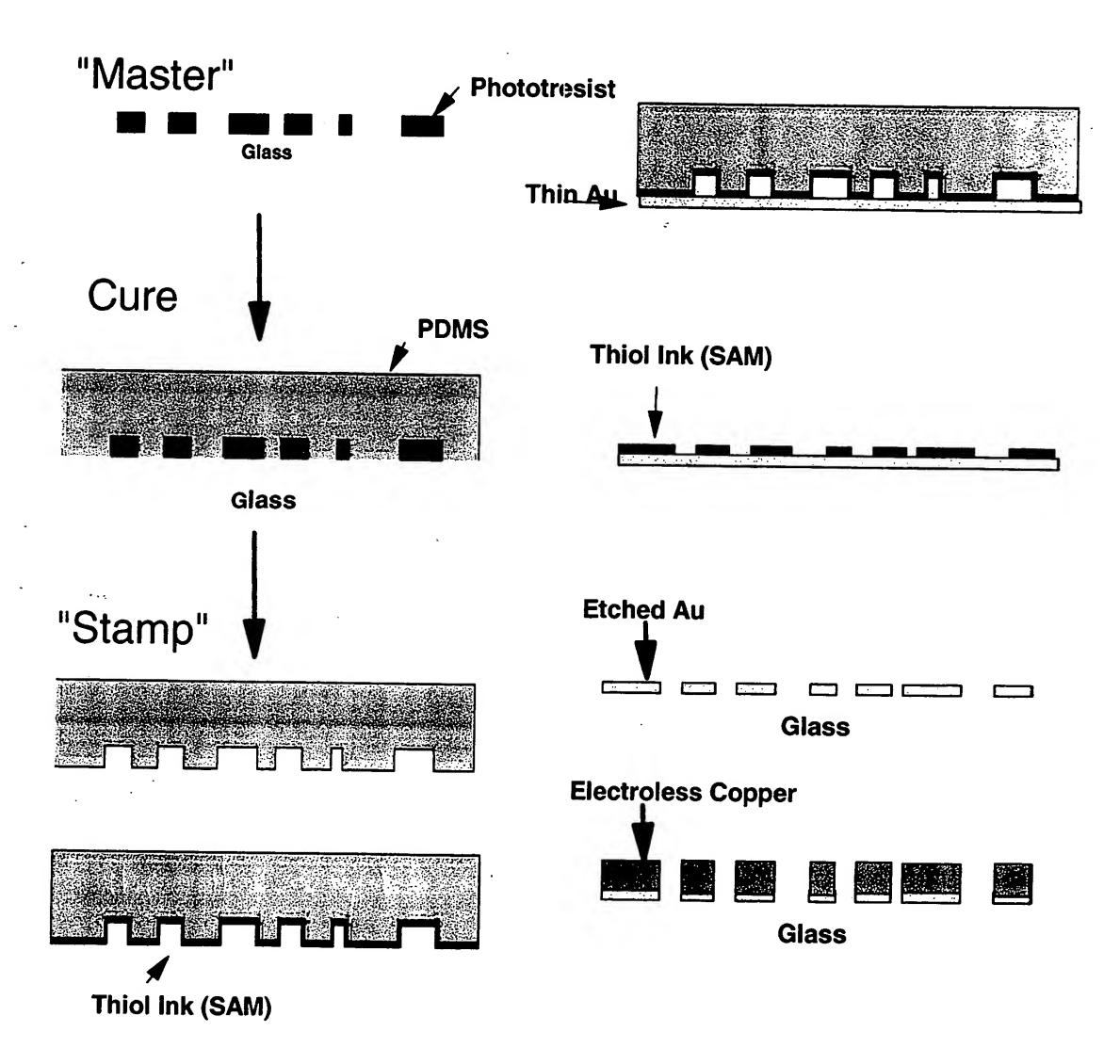
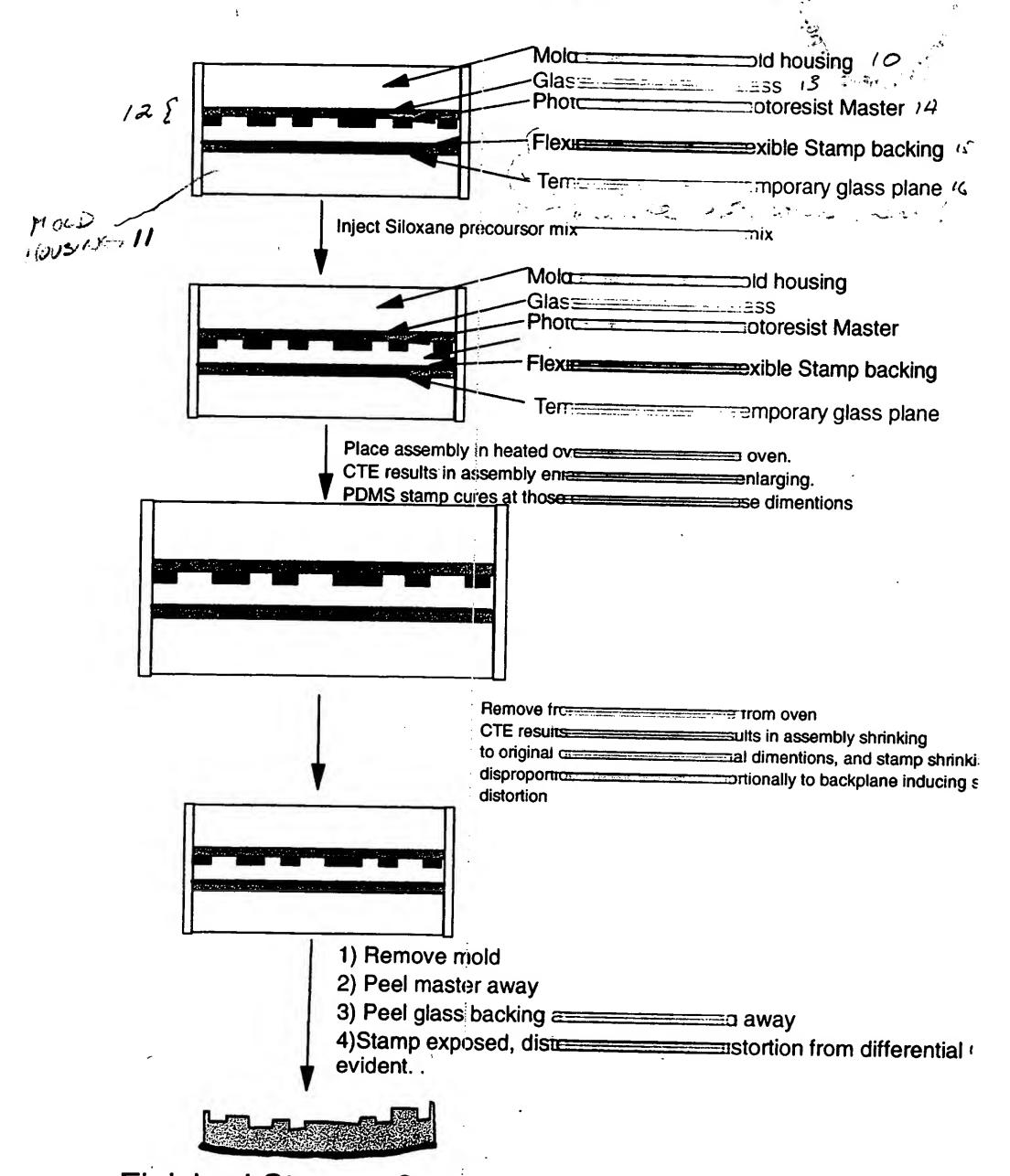
Figure 1: Printing and Plating. Typical schemetic proceedure for making stamp from photoresist master pattern, inking with thiol, stamping thiol on gold to form SAM protective pattern, etching away unprotected gold, electroless plating of copper

lines on top of remaining gold.



## Figure 2: Standard one-ster p curing me



Finished Stamp - Severe dis-

## Figure 3: Two stage curing siloxane stamp. Mold housing 2 6 Glass ZZ Photoresist Master 23 Flexible Stamp backing 24 Temporary glass plane 25 Inject Siloxane precoursor mix MOLD 21 t-Fozi Nis Mold housing 20 Glass 22 Photoresist Master 23 Flexible Stamp backing 2 4 Temporary glass plane 25 Hold at Room temperature to carry out 21 A-stage cure. In this way the pattern geometry is fixed at end-use thermal conditions. Typically hold for 1 week. Insert full assembly for higher temperature post-cure hardening. The small fraction of unreacted crosslink functional groups now react and harden the material. 1) Return assembly to room temperature 2) Remove mold 3) Peel master away 4) Peel glass backing away

Finished Stamp - Little distortion evident

evident. .

5)Stamp exposed, and distrortion free pattern is